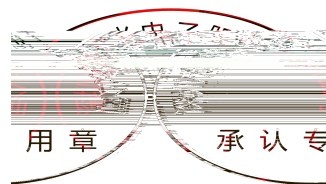
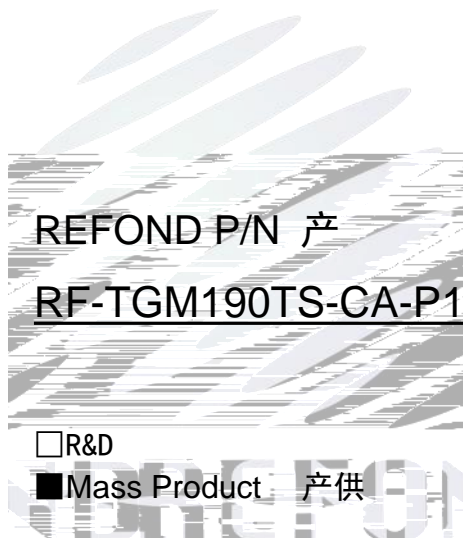
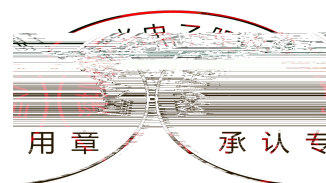
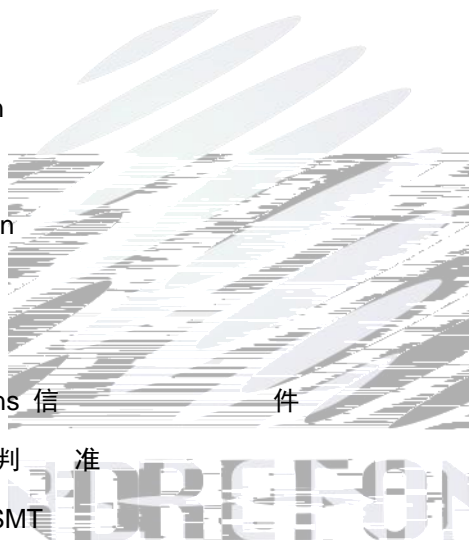


SPECIFICATION 产 书



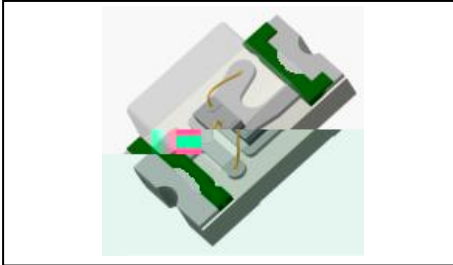
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 - 1.1 General Description 产
 - 1.2 Features 产
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1. Description 产 介

1.1 General Description 产



The Colour LED which was fabricated using a green chip, Package Dimension : 1.6mmX0.8mmX0.4mm.

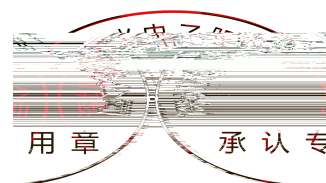
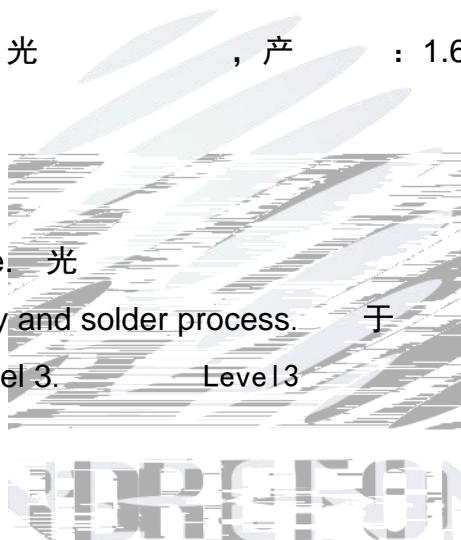
产 为 光 LED, 光 , 产 : 1.6mmX0.8mmX0.4mm。

1.2 Features 产

- Extremely wide viewing angle. 光
- Suitable for all SMT assembly and solder process. 于 SMT
- Moisture sensitivity level: Level 3. Level 3
- RoHS compliant. RoHS

1.3 Application 产

- Optical indicator. 光
- Switch and symbol, display. 关 ,
- General use. 其他



1.4 Package Dimension

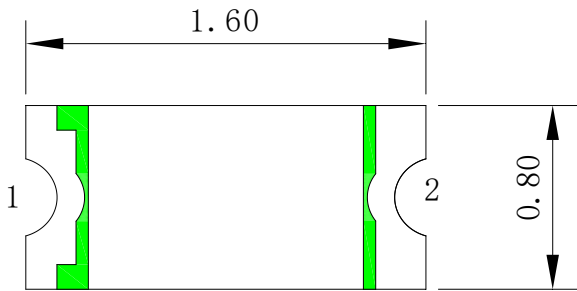


Fig.1-1 Top view

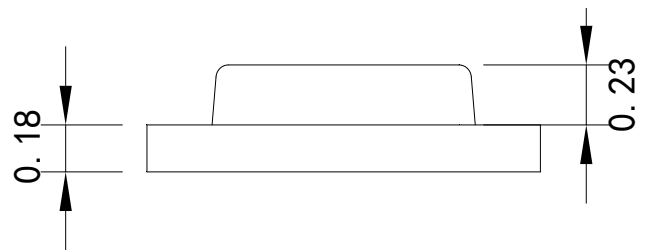


Fig.1-2 Side view 側

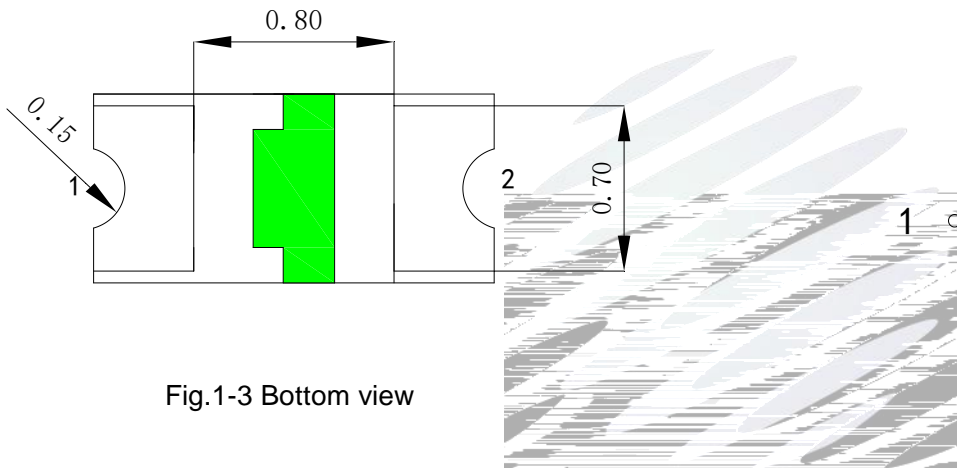


Fig.1-3 Bottom view

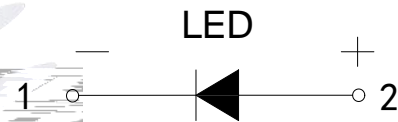


Fig.1-4 Polarity

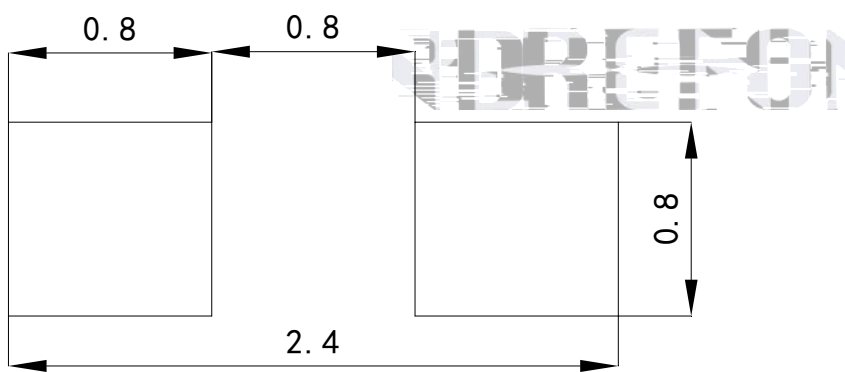


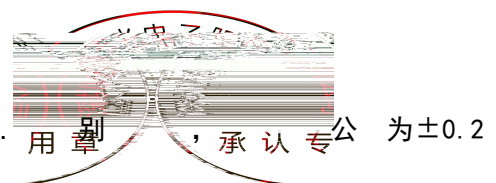
Fig.1-5 Soldering patterns

Notes :

1. All dimensions units are millimeters.

单位为

All dimensions tolerances are ± 0.2 mm unless otherwise noted.



1.5 Product Parameters 产

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 与光

Item	Test Condition 件	Symbol	Value			Unit 单位	
			Min. (值)	Typ. (典 值)	Max. (值)		
Spectral Half Bandwidth 半	I _F =2mA	△	--	15	--	nm	
Forward Voltage	I _F =2mA	V _F	D2	2.3	--	2.4	V
			E1	2.4	--	2.5	V
			E2	2.5	--	2.6	V
			F1	2.6	--	2.7	V
			F2	2.7	--	2.8	V
			G1	2.8	--	2.9	V
			G2	2.9	--	3.0	V
Dominant Wavelength 主	I _F =2mA	D	F10	525	--	527.5	nm
			F20	527.5	--	530	nm
			G10	530	--	532.5	nm
			G20	532.5	--	535	nm
Luminous Intensity 光	I _F =2mA	I _v	FD0	90	--	100	mcd
			GA0	100	--	110	mcd
			GB0	110	--	120	mcd
			1FJ	120	--	130	mcd
			1FQ	130	--	140	mcd
			1FR	140	--	150	mcd
			1FS	150	--	160	mcd
Viewing Angle 光	I _F =2mA	2 1/2	--	140	--	deg	
Reverse Current	V _R =5V	I _R	--	--	10	μA	
Thermal Resistance.	I _F =2mA	R _{THJ-S}	--	--	450	°C/W	

Notes : V_R=5V For test conditions. V_R=5V 为 分 件。

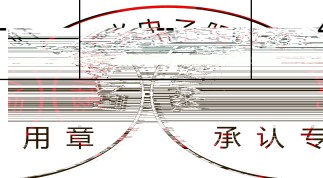


Table 1-2 Absolute Maximum Ratings at Ts=25°C 值

Parameter ()	Symbol ()	Rating (值)	Units (单位)
Power Dissipation (功)	P _d	60	mW
Forward Current ()	I _F	20	mA
Peak Forward Current Of Pulse (冲值)	I _{FP}	60	mA
Electrostatic Discharge (HBM) ()	E _{SD}	1000	V
Operating Temperature (作,)			

Notes :

- 1/10 Duty cycle, 0.1ms pulse width. 0.1ms, 占 1/10.
- The above forward voltage measurement allowance tolerance is ±0.1V. 以上 ±0.1V.
- The above dominant wavelength measurement allowance tolerance is ±2nm. 以主 ±2nm.
- The above luminous intensity measurement allowance tolerance ±10%. 上 光 允 公 为 ±10%.
- Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使 功 不 值。
- All measurements were made under the standardized environment of Refond. 于 丰 准 。
- When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED 使 件 , 不 值。

1.6 Typical Optical Characteristics Curves 典 光

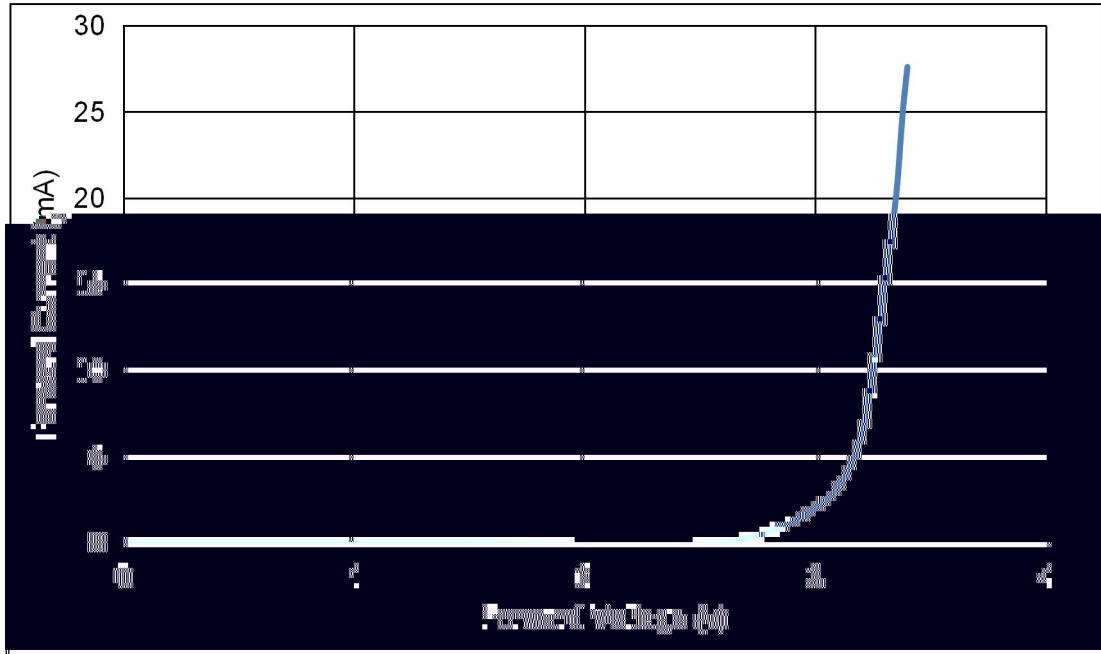


Fig 1-6 Forward Voltage Vs Forward Current 伏

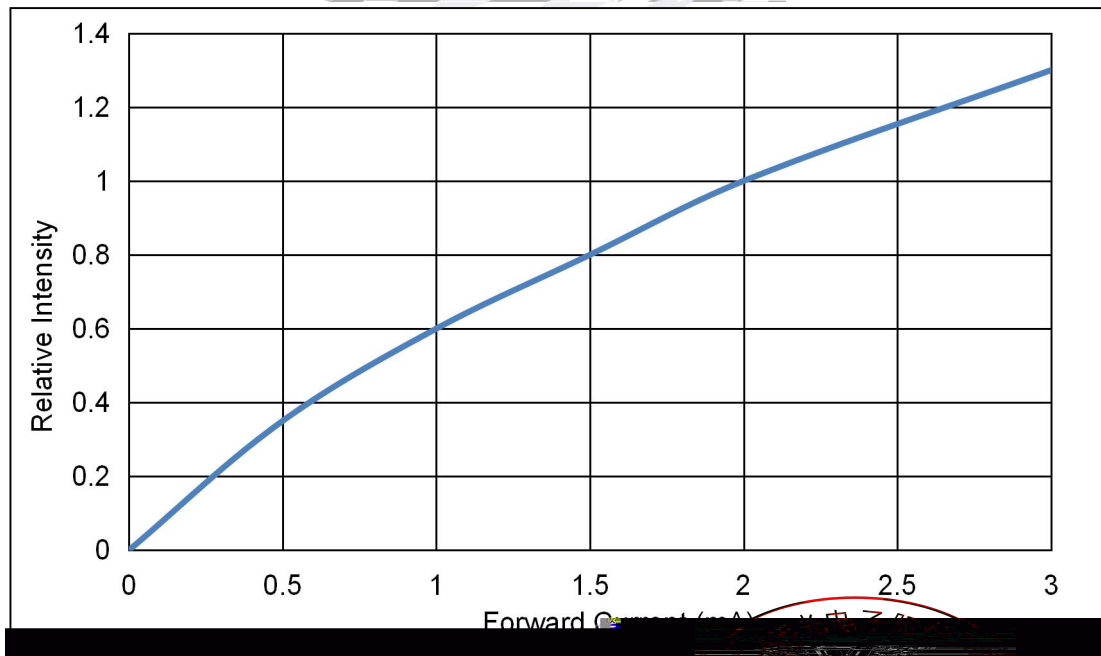
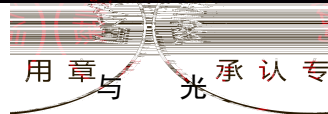


Fig 1-7 Forward Current Vs Relative Intensity



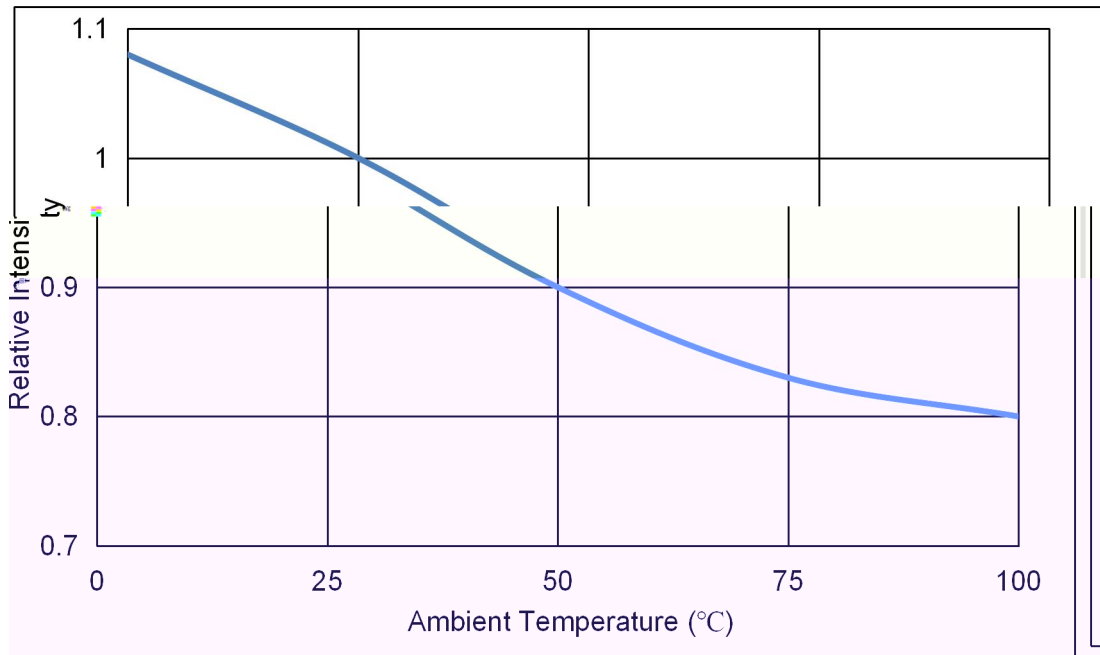


Fig 1-8 Pin Temperature Vs Relative Intensity 与 光

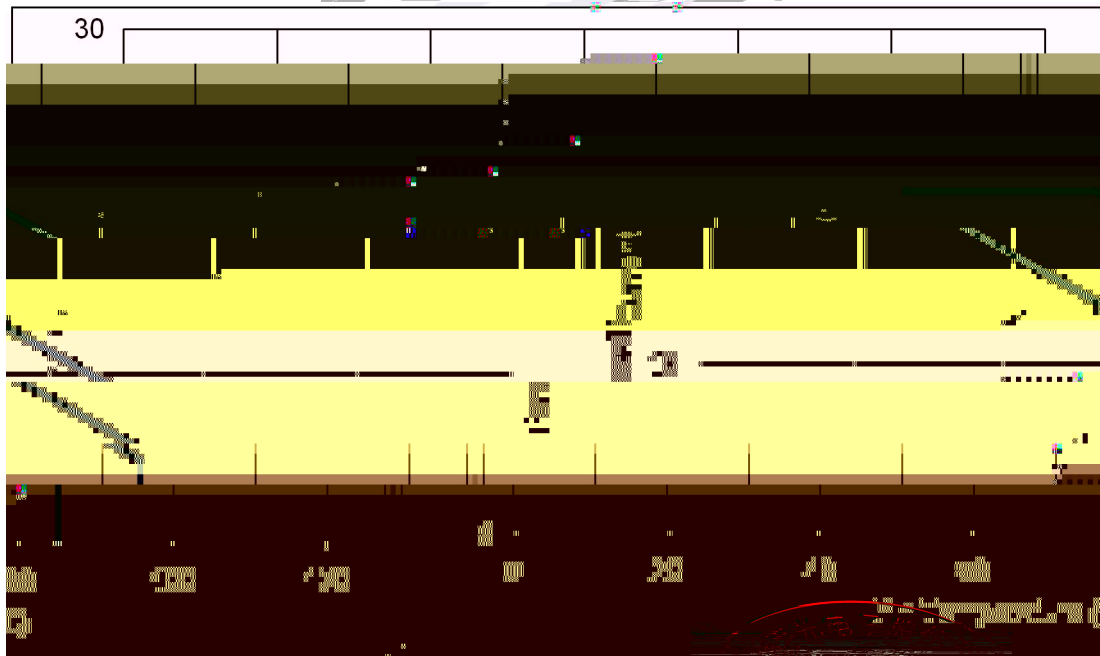


Fig 1-9 Pin Temperature Vs Forward Current



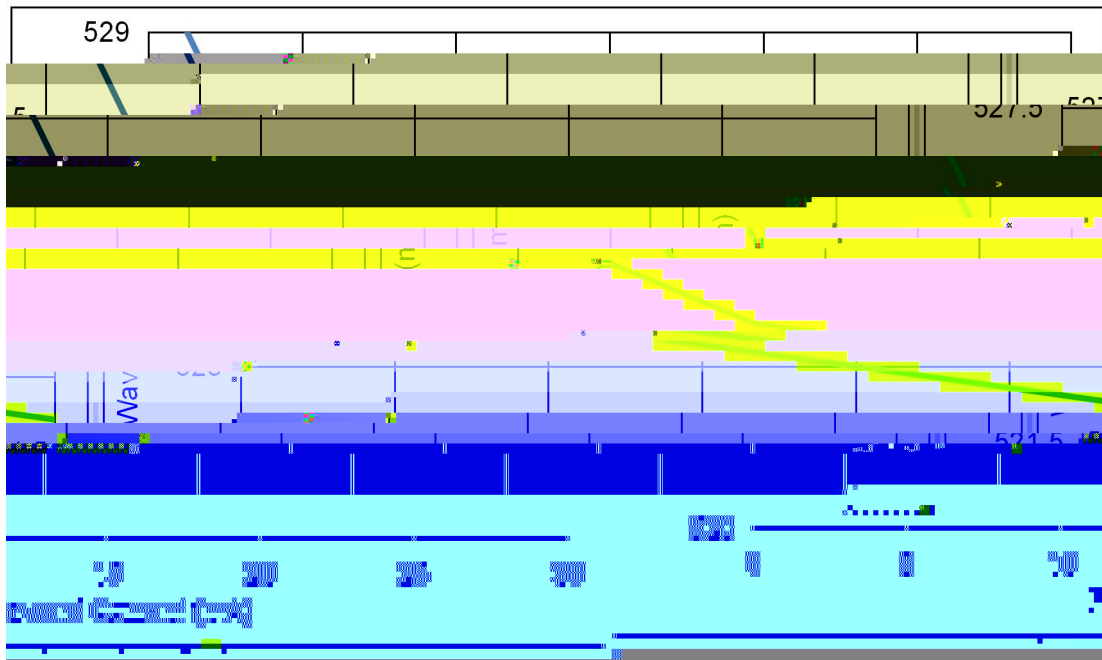


Fig 1-10 Forward Current Vs Dominate Wavelength (Ta=25°C)

与主 关

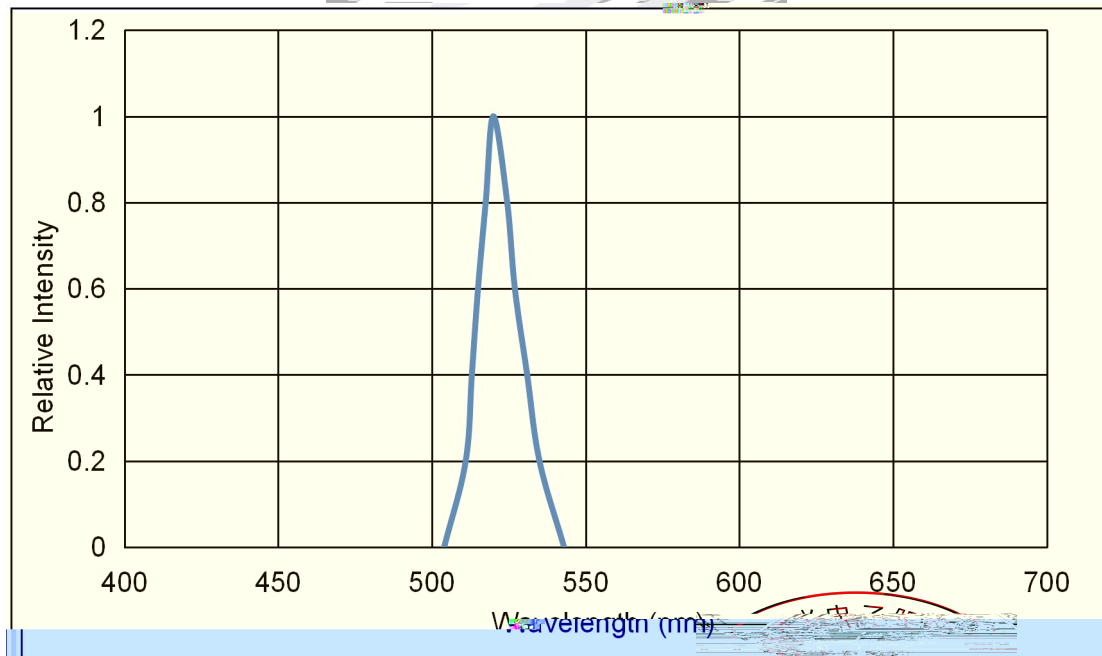
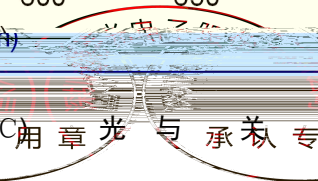


Fig 1-11 Relative Intensity Vs Wavelength (Ta=25°C)



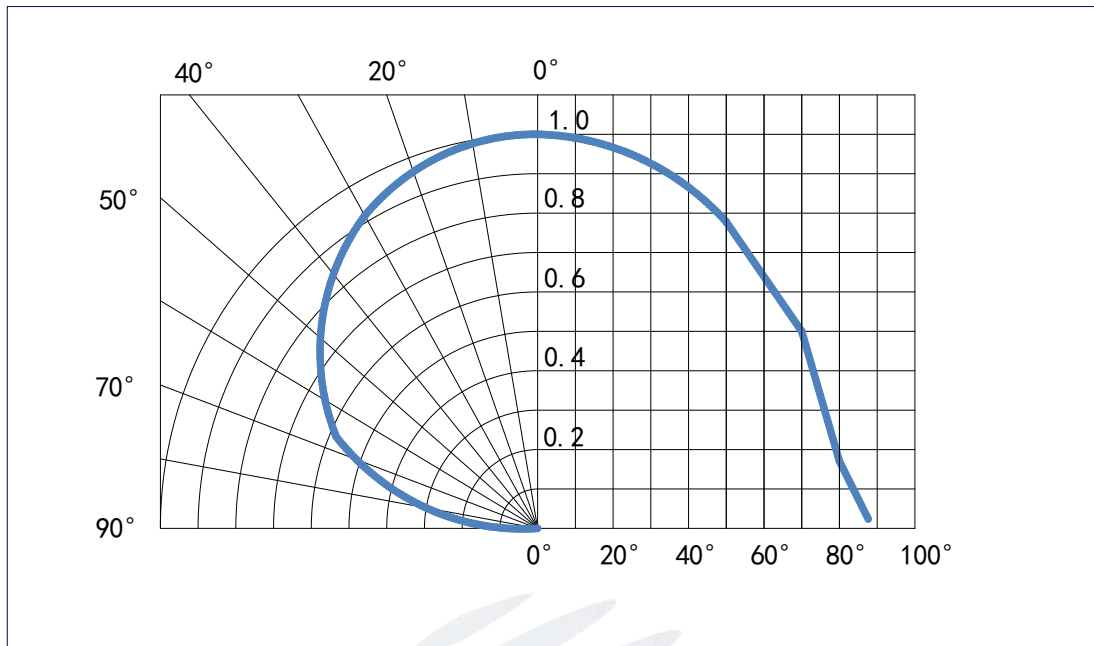
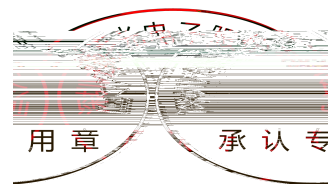


Fig 1-12 Diagram characteristics of radiation



2. Packaging 产 包

2.1 Packaging Specification 包

Package:4000pcs/reel.包 4000pcs。



2.1.1 Carrier Tape Dimension

Fig.2-1 Carrier Tape Dimension

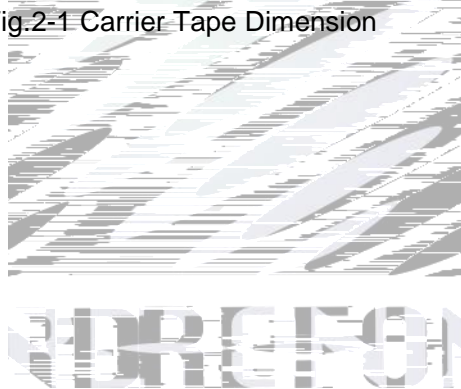


Table 2-1 Dimension

A	8.0±0.1mm
B	178±1mm
C	60±1mm
D	13.0±0.5mm

2.1.2 Reel Dimension

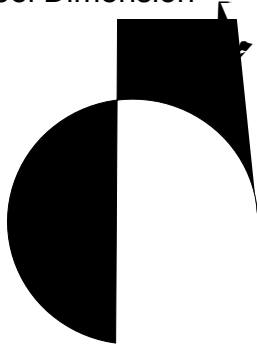


Fig.2-2 Reel Dimension



Notes :

The tolerances unless mentioned ±0.1mm. Unit : mm : 公 为 ±0.1 , 单位: 。

2.1.3 Label Form Specification

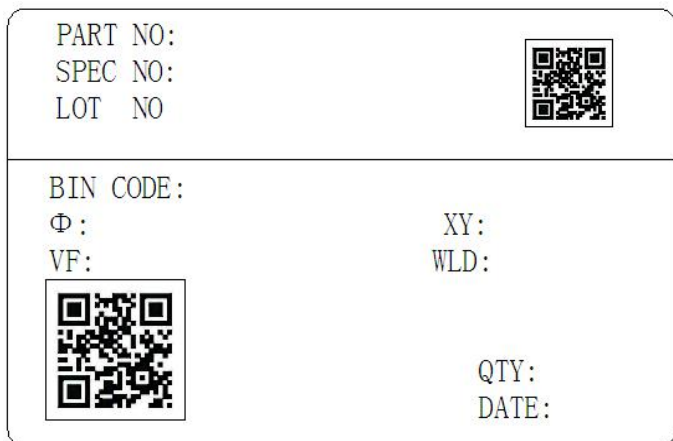


Fig. 2-3 Label Form Specification

Table 2-2 Parameter

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code 代
	Luminous flux 光
XY	Chromaticity Bin 区
V _F	Forward Voltage
WLD	Wavelength 代
QTY	Packing Quantity
DATE	Made Date 产

2.2 Moisture Resistant Packing 包



Fig.2-4 Moisture Resistant Packing 包

Cardboard Box 包

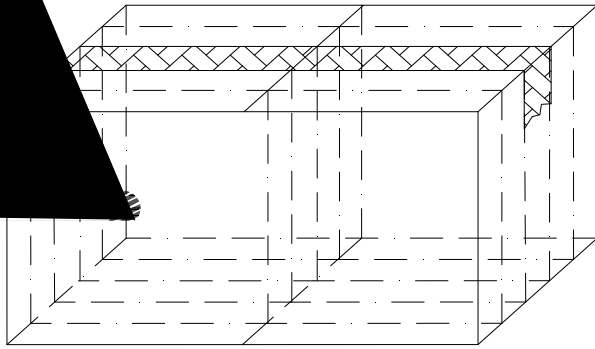


Fig.2-5 Cardboard Box 包

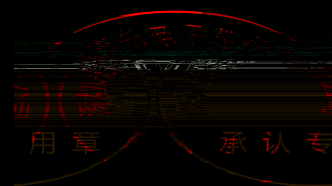
2.4 Reliability Test Items And Conditions 信

件

Table 2-3 Reliability Test Items And Conditions 信

件

Test Items	Ref.Standard 准	Test Condition 件	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	T _{emp} :260°Cmax T=10 sec	2 times	22Pcs.	0/1
Temperature Cycle	JESD22-A104	100°C 30 min 5 min -40°C 30 min	100 cycles	22Pcs.	0/1
Thermal Shock 冲击	JESD22-A106	-40°C 15min 100°C 15min	300 cycles	22Pcs.	0/1



2.5 Criteria For Judging Damage 判 准

Table 2-4 Criteria For Judging Damage 判 准

Test Items	Symbol	Test Condition 件	Criteria For Judgement 判 准	
			Min.	Max.
Forward Voltage	V_F	$I_F=2mA$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R= 5V$	-	U.S.L*)x2.0
Luminous Flux 光		$I_F=2mA$	L.S.L*)x0.7	-

Notes :

1.U.S.L: Upper standard level

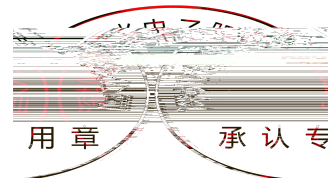
上

L.S.L: Lower standard level

下

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. 以上 于 丰 单 / LED 件 下 。 LED 于串、 , 估 、 分 、 。

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上 仅为产 典 值, 作为 , 不作为任何 件 保 。



3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

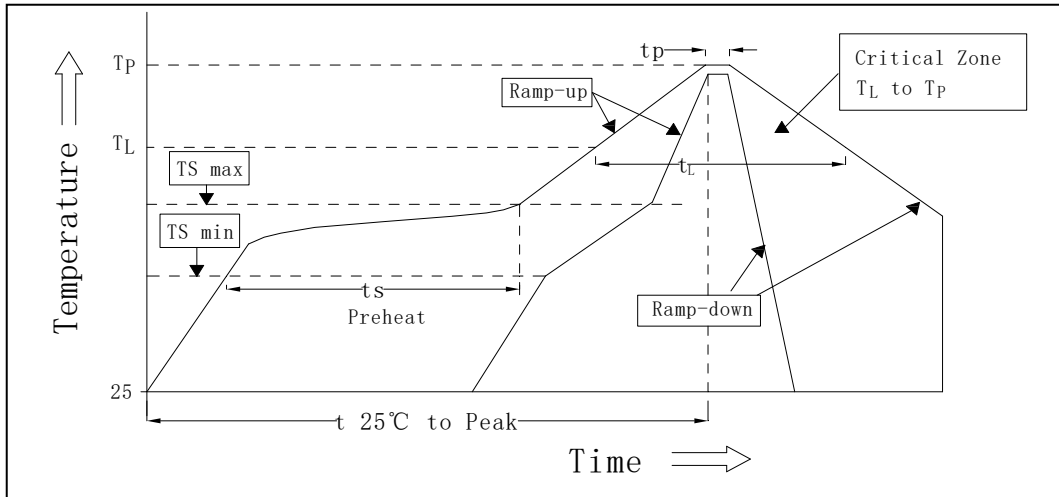


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameter

Average temperature rise speed	升 (T _{smax} - T _P)	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	: 低 (T _{smin})	150 °C
Preheating: Max temperature	: (T _{smax})	200 °C
Preheating: Time	: (T _{smin} - T _{smax})	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature	: (T _L)	217 °C
Time limited to maintain high temperature: The Time	: (t _L)	60 Max 60s
Peak /Classification of temperature: 值 / 分 (T _P)		260 °C
Time limit classification of peak temperature time 值分	: (t _p)	10 Max 10s
Hold time within 5 ° C with the actual peak temperature (TP) 与 值 (T _P) 5 °C 以内 保		30 Max 30s
Cooling speed		6 °C/ Max 6 °C/ s
Needed time from 25 °C to T _p 25 °C 升 值		8分 Max 8 minutes

Notes :

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 不以两, 两 24 , LED 于

(2)When soldering , do not put stress on the LEDs during heating. , 不 力 体

3.1.1 Soldering Iron

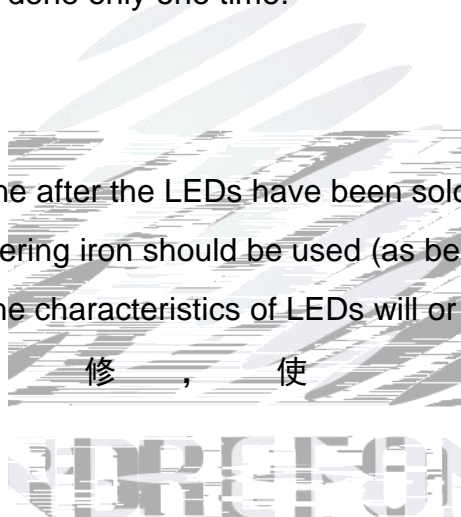
(1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds. , 于300°C, 不 3 。

(2) Soldering by hand should be done only one time. 一 。

3.1.2 Repairing 修

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

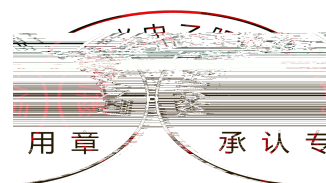
LED 不 修 , 修 , 使 , 且事先 会不 会 LED 。



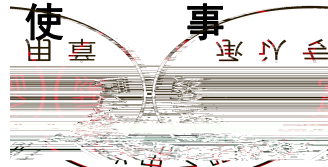
3.1.3 Cautions 事

(1) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED 不 PCB 上, 之 , 也不 。

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering. 之 冷却 中, 不 加 力, 也不 动, , 不 剧冷却 。



4. Handling Precautions 产 使 事



4.1 Handling Precautions 产 使 事

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 作 与 LED 中 元 化 份 不 100PPM.

一个 ，不作任何 保。

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. 为了 入 LED 内 以 LED 伤,

件 ，单一 元 于 900PPM, 单一 元 于 900PPM, 元 与 元 于 1500PPM. 一个 ，不作任何 保。

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. 件中 会 到 LED 内 ， 产 光

件下，会 LED ， 严 光 ， 前了 件 免产 些 。
 丰 使 任何 LED 件 ，不 些 了
 仅仅 。 使 ， 丰
 。 LED

(4) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

不 值, , 使保 , 则, 化会
化, 产 。 保 关 候出 化, 不
加 , 则会 LED。

(5) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED 为

, 升会低LED光 , 光 , 以 充分

(6) Storage

Table 4-1 Storage 储

Conditions		Temperature	Humidity	Time
Storage 储	Before Opening Aluminum Bag 包前	≤30°C	≤75%	Within 1 Year From Date 一 内
	After Opening Aluminum Bag 包	≤30°C	≤60%	168hours 168
Baking		60±5°C	-	≥24hours 于24

(7) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition (60 ± 5) °C for above 24 hours. 剂包 , 产不 以上

储 件, 包 , 件: 60±5°C, 于24 以上。

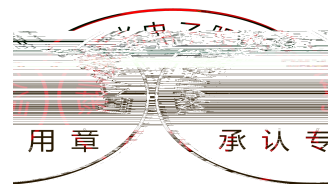
If the package is flatulence or damaged, please notify the sales staff to assist. 包

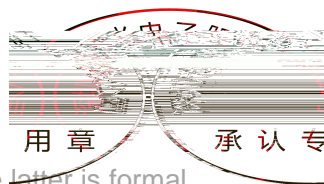
, 人 协助 。



(8) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 像其他 半 体 件一 , LED 击 , 做 。

(9) Other points for attention, please refer to our relevant information.其 事 丰 关 。





Declare

This specification is written both in English and in Chinese and the latter is formal.

产 书以中 书写, 冲 以中 为准。